

# HEF4053B

## Triple single-pole double-throw analog switch

Rev. 12 — 25 March 2016

Product data sheet

### 1. General description

The HEF4053B is a triple single-pole double-throw (SPDT) analog switch, suitable for use as an analog or digital multiplexer/demultiplexer. Each switch has a digital select input ( $S_n$ ), two independent inputs/outputs ( $nY_0$  and  $nY_1$ ) and a common input/output ( $nZ$ ). All three switches share an enable input ( $\bar{E}$ ). A HIGH on  $\bar{E}$  causes all switches into the high-impedance OFF-state, independent of  $S_n$ .

$V_{DD}$  and  $V_{SS}$  are the supply voltage connections for the digital control inputs ( $S_n$  and  $\bar{E}$ ). The  $V_{DD}$  to  $V_{SS}$  range is 3 V to 15 V. The analog inputs/outputs ( $nY_0$ ,  $nY_1$  and  $nZ$ ) can swing between  $V_{DD}$  as a positive limit and  $V_{EE}$  as a negative limit.  $V_{DD} - V_{EE}$  may not exceed 15 V. Unused inputs must be connected to  $V_{DD}$ ,  $V_{SS}$ , or another input. For operation as a digital multiplexer/demultiplexer,  $V_{EE}$  is connected to  $V_{SS}$  (typically ground).  $V_{EE}$  and  $V_{SS}$  are the supply voltage connections for the switches.

### 2. Features and benefits

- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Complies with JEDEC standard JESD 13-B

### 3. Applications

- Analog multiplexing and demultiplexing
- Digital multiplexing and demultiplexing
- Signal gating

### 4. Ordering information

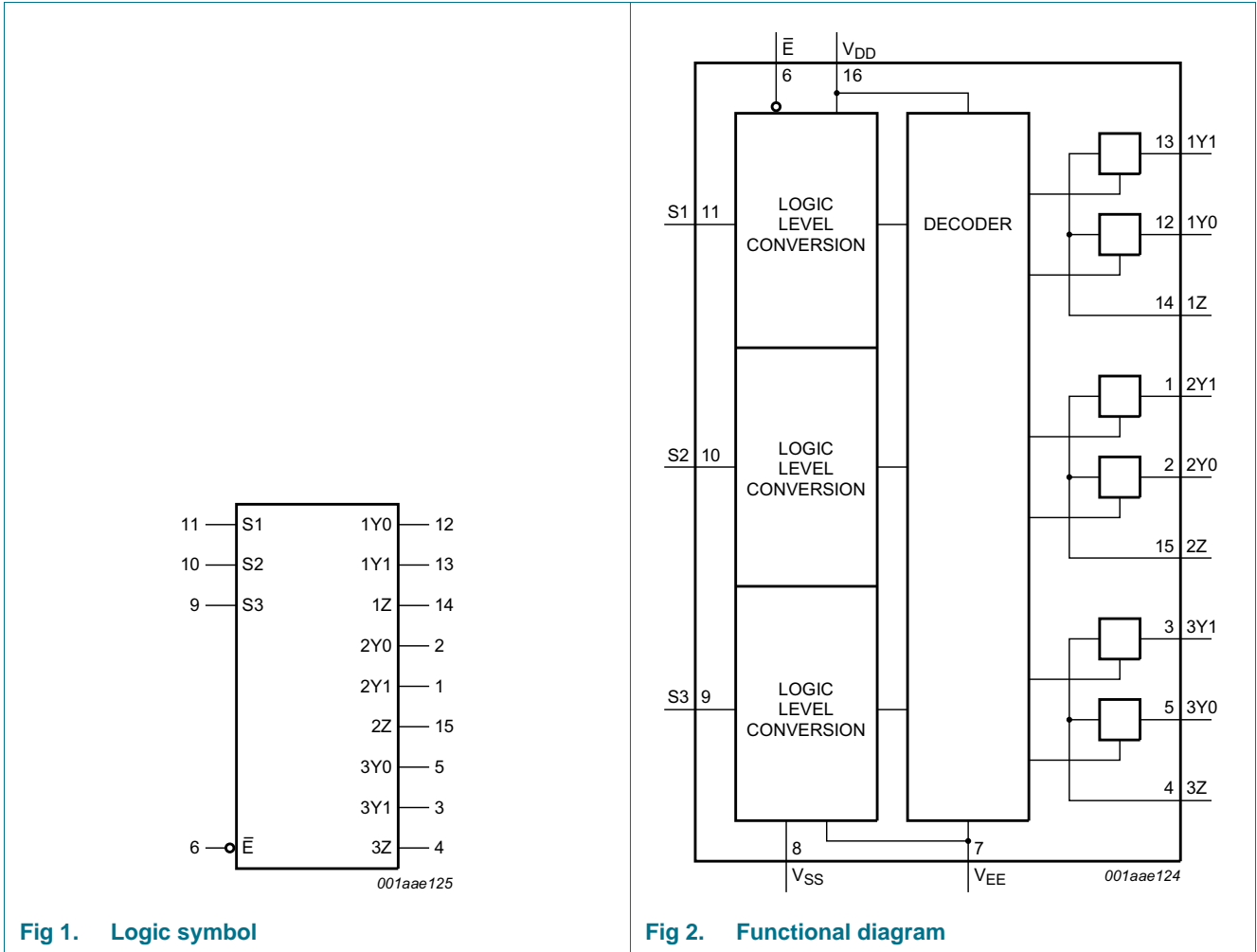
Table 1. Ordering information

All types operate from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$ .

Type number	Package		Version
	Name	Description	
HEF4053BT	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
HEF4053BTT	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1

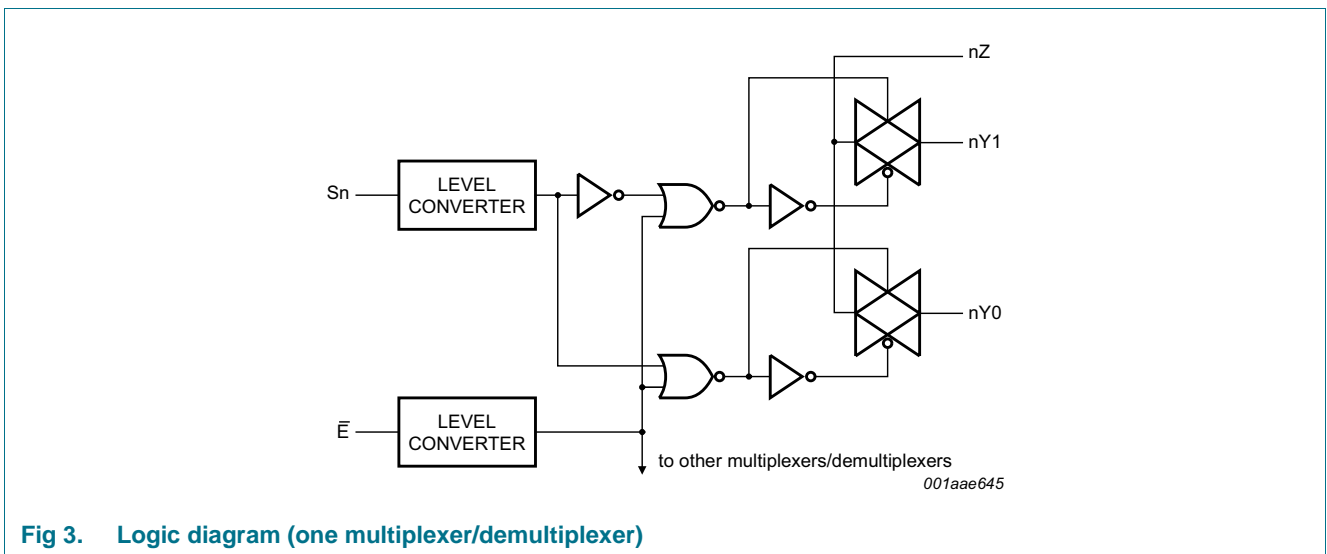


**5. Functional diagram**



**Fig 1. Logic symbol**

**Fig 2. Functional diagram**



**Fig 3. Logic diagram (one multiplexer/demultiplexer)**

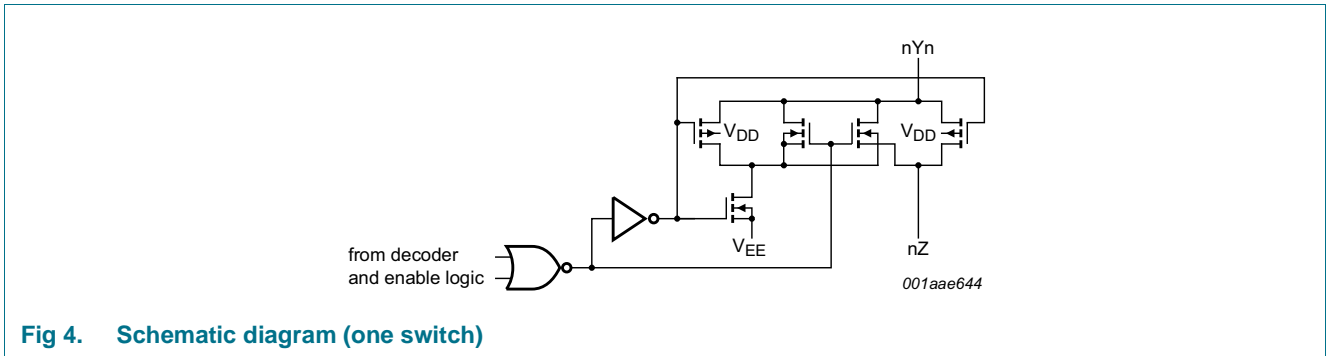


Fig 4. Schematic diagram (one switch)

## 6. Pinning information

### 6.1 Pinning

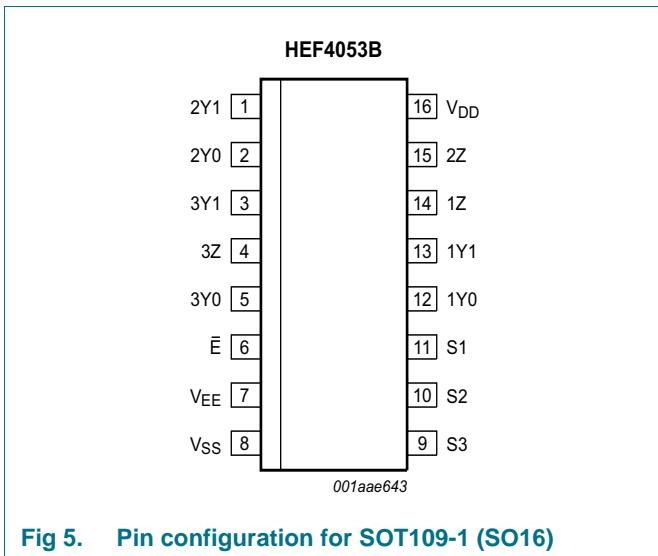


Fig 5. Pin configuration for SOT109-1 (SO16)

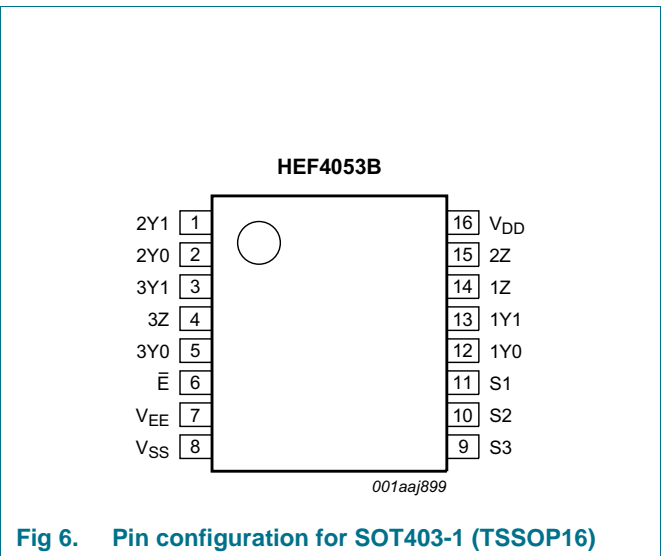


Fig 6. Pin configuration for SOT403-1 (TSSOP16)

### 6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\bar{E}$	6	enable input (active LOW)
$V_{EE}$	7	supply voltage
$V_{SS}$	8	ground supply voltage
S1, S2, S3	11, 10, 9	select input
1Y0, 2Y0, 3Y0	12, 2, 5	independent input or output
1Y1, 2Y1, 3Y1	13, 1, 3	independent input or output
1Z, 2Z, 3Z	14, 15, 4	independent output or input
$V_{DD}$	16	supply voltage

## 7. Functional description

Table 3. Function table [1]

Inputs		Channel on
$\bar{E}$	Sn	
L	L	nY0 to nZ
L	H	nY1 to nZ
H	X	switches OFF

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care.

## 8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to  $V_{SS} = 0$  V (ground).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DD}$	supply voltage		-0.5	+18	V
$V_{EE}$	supply voltage	referenced to $V_{DD}$ [1]	-18	+0.5	V
$I_{IK}$	input clamping current	pins Sn and $\bar{E}$ ; $V_I < -0.5$ V or $V_I > V_{DD} + 0.5$ V	-	$\pm 10$	mA
$V_I$	input voltage		-0.5	$V_{DD} + 0.5$	V
$I_{I/O}$	input/output current		-	$\pm 10$	mA
$I_{DD}$	supply current		-	50	mA
$T_{stg}$	storage temperature		-65	+150	°C
$T_{amb}$	ambient temperature		-40	+125	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C			
		SO16 package [2]	-	500	mW
		TSSOP16 package [2]	-	500	mW
P	power dissipation	per output	-	100	mW

[1] To avoid drawing  $V_{DD}$  current out of terminal Z, when switch current flows into terminals Y, the voltage drop across the bidirectional switch must not exceed 0.4 V. If the switch current flows into terminal Z, no  $V_{DD}$  current will flow out of terminals Y, and in this case there is no limit for the voltage drop across the switch, but the voltages at Y and Z may not exceed  $V_{DD}$  or  $V_{EE}$ .

[2] For SO16 package:  $P_{tot}$  derates linearly with 8 mW/K above 70 °C.  
For TSSOP16 package:  $P_{tot}$  derates linearly with 5.5 mW/K above 60 °C.

## 9. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DD}$	supply voltage	see <a href="#">Figure 7</a>	3	-	15	V
$V_I$	input voltage		0	-	$V_{DD}$	V
$T_{amb}$	ambient temperature	in free air	-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{DD} = 5$ V	-	-	3.75	$\mu\text{s/V}$
		$V_{DD} = 10$ V	-	-	0.5	$\mu\text{s/V}$
		$V_{DD} = 15$ V	-	-	0.08	$\mu\text{s/V}$

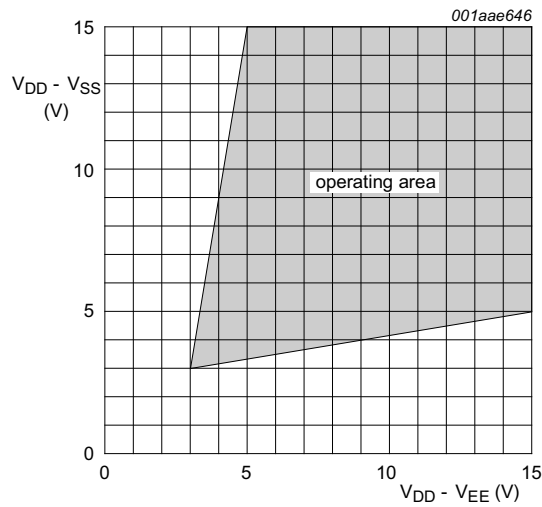


Fig 7. Operating area as a function of the supply voltages

### 10. Static characteristics

Table 6. Static characteristics

$V_{SS} = V_{EE} = 0\text{ V}$ ;  $V_I = V_{SS}$  or  $V_{DD}$  unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	$T_{amb} = -40\text{ }^{\circ}\text{C}$		$T_{amb} = 25\text{ }^{\circ}\text{C}$		$T_{amb} = 85\text{ }^{\circ}\text{C}$		$T_{amb} = 125\text{ }^{\circ}\text{C}$		Unit
				Min	Max	Min	Max	Min	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	3.5	-	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	11.0	-	V
$V_{IL}$	LOW-level input voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	-	1.5	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	-	4.0	V
$I_I$	input leakage current		15 V	-	$\pm 0.1$	-	$\pm 0.1$	-	$\pm 1.0$	-	$\pm 1.0$	$\mu\text{A}$
$I_{S(OFF)}$	OFF-state leakage current	Z port; all channels OFF; see <a href="#">Figure 8</a>	15 V	-	-	-	1000	-	-	-	-	nA
		Y port; per channel; see <a href="#">Figure 9</a>	15 V	-	-	-	200	-	-	-	-	nA
$I_{DD}$	supply current	$I_O = 0\text{ A}$	5 V	-	5	-	5	-	150	-	150	$\mu\text{A}$
			10 V	-	10	-	10	-	300	-	300	$\mu\text{A}$
			15 V	-	20	-	20	-	600	-	600	$\mu\text{A}$
$C_I$	input capacitance	$S_n, \bar{E}$ inputs	-	-	-	-	7.5	-	-	-	-	pF

10.1 Test circuits

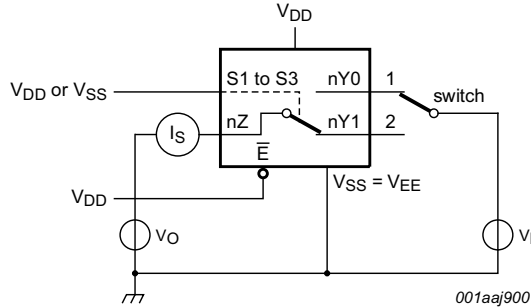


Fig 8. Test circuit for measuring OFF-state leakage current Z port

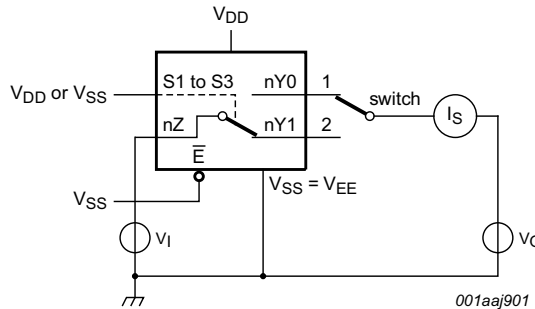


Fig 9. Test circuit for measuring OFF-state leakage current nYn port

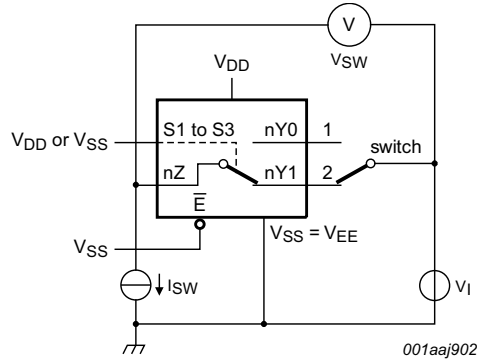
10.2 ON resistance

Table 7. ON resistance

$T_{amb} = 25\text{ }^{\circ}\text{C}$ ;  $I_{SW} = 200\text{ }\mu\text{A}$ ;  $V_{SS} = V_{EE} = 0\text{ V}$ .

Symbol	Parameter	Conditions	$V_{DD} - V_{EE}$	Typ	Max	Unit
$R_{ON(peak)}$	ON resistance (peak)	$V_I = 0\text{ V to }V_{DD} - V_{EE}$ ; see <a href="#">Figure 10</a> and <a href="#">Figure 11</a>	5 V	350	2500	$\Omega$
			10 V	80	245	$\Omega$
			15 V	60	175	$\Omega$
$R_{ON(rail)}$	ON resistance (rail)	$V_I = 0\text{ V}$ ; see <a href="#">Figure 10</a> and <a href="#">Figure 11</a>	5 V	115	340	$\Omega$
			10 V	50	160	$\Omega$
			15 V	40	115	$\Omega$
		$V_I = V_{DD} - V_{EE}$ ; see <a href="#">Figure 10</a> and <a href="#">Figure 11</a>	5 V	120	365	$\Omega$
			10 V	65	200	$\Omega$
			15 V	50	155	$\Omega$
$\Delta R_{ON}$	ON resistance mismatch between channels	$V_I = 0\text{ V to }V_{DD} - V_{EE}$ ; see <a href="#">Figure 10</a>	5 V	25	-	$\Omega$
			10 V	10	-	$\Omega$
			15 V	5	-	$\Omega$

10.2.1 ON resistance waveform and test circuit



$$R_{ON} = V_{SW} / I_{SW}$$

Fig 10. Test circuit for measuring  $R_{ON}$

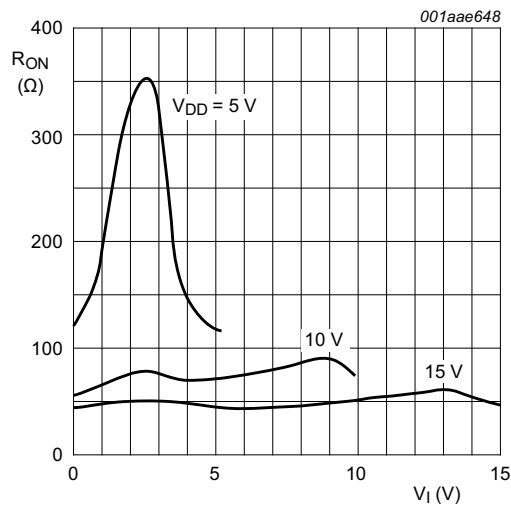


Fig 11. Typical  $R_{ON}$  as a function of input voltage

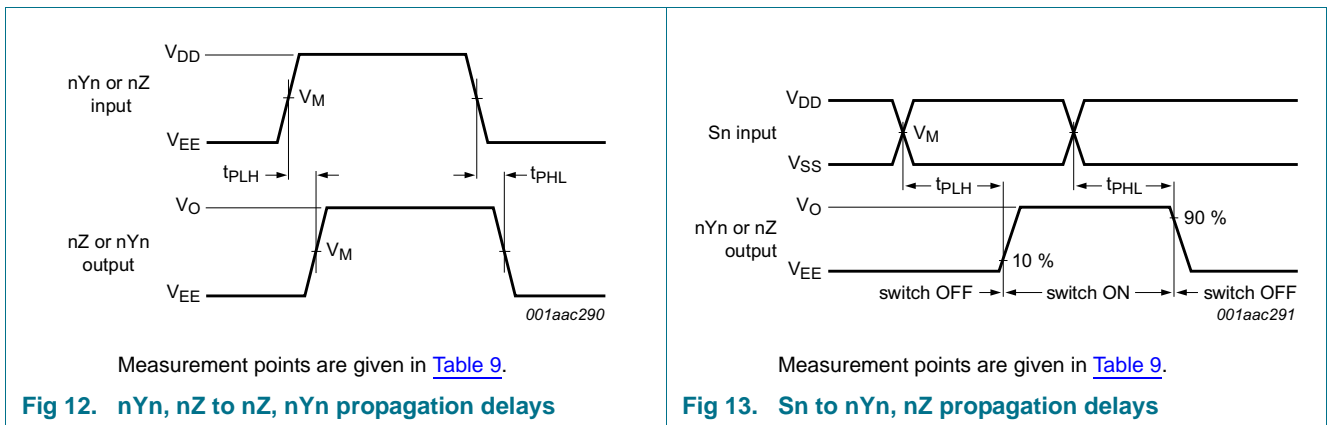
## 11. Dynamic characteristics

**Table 8. Dynamic characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$ ;  $V_{SS} = V_{EE} = 0\text{ V}$ ; for test circuit see [Figure 15](#).

Symbol	Parameter	Conditions	$V_{DD}$	Typ	Max	Unit
$t_{PHL}$	HIGH to LOW propagation delay	nYn, nZ to nZ, nYn; see <a href="#">Figure 12</a>	5 V	10	20	ns
			10 V	5	10	ns
			15 V	5	10	ns
		Sn to nYn, nZ; see <a href="#">Figure 13</a>	5 V	200	400	ns
			10 V	85	170	ns
			15 V	65	130	ns
$t_{PLH}$	LOW to HIGH propagation delay	nYn, nZ to nZ, nYn; see <a href="#">Figure 12</a>	5 V	15	30	ns
			10 V	5	10	ns
			15 V	5	10	ns
		Sn to nYn, nZ; see <a href="#">Figure 13</a>	5 V	275	555	ns
			10 V	100	200	ns
			15 V	65	130	ns
$t_{PHZ}$	HIGH to OFF-state propagation delay	$\bar{E}$ to nYn, nZ; see <a href="#">Figure 14</a>	5 V	200	400	ns
			10 V	115	230	ns
			15 V	110	220	ns
$t_{PZH}$	OFF-state to HIGH propagation delay	$\bar{E}$ to nYn, nZ; see <a href="#">Figure 14</a>	5 V	260	525	ns
			10 V	95	190	ns
			15 V	65	130	ns
$t_{PLZ}$	LOW to OFF-state propagation delay	$\bar{E}$ to nYn, nZ; see <a href="#">Figure 14</a>	5 V	200	400	ns
			10 V	120	245	ns
			15 V	110	215	ns
$t_{PZL}$	OFF-state to LOW propagation delay	$\bar{E}$ to nYn, nZ; see <a href="#">Figure 14</a>	5 V	280	565	ns
			10 V	105	205	ns
			15 V	70	140	ns

### 11.1 Waveforms and test circuit





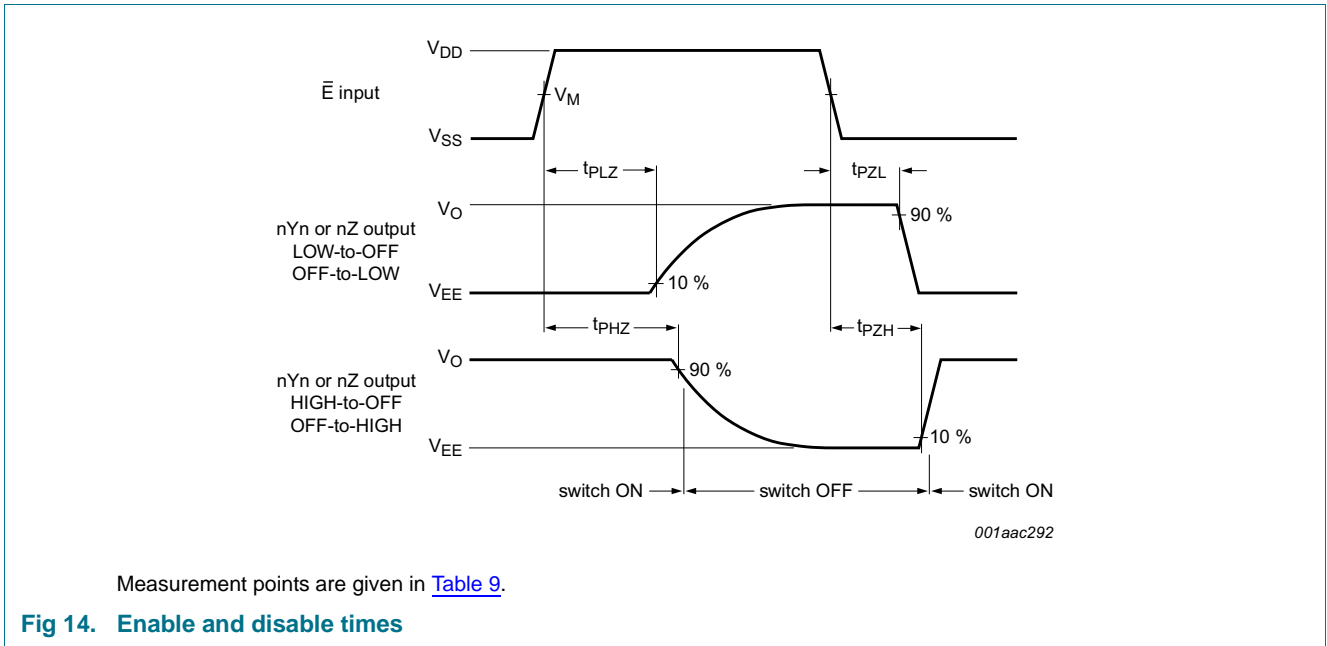
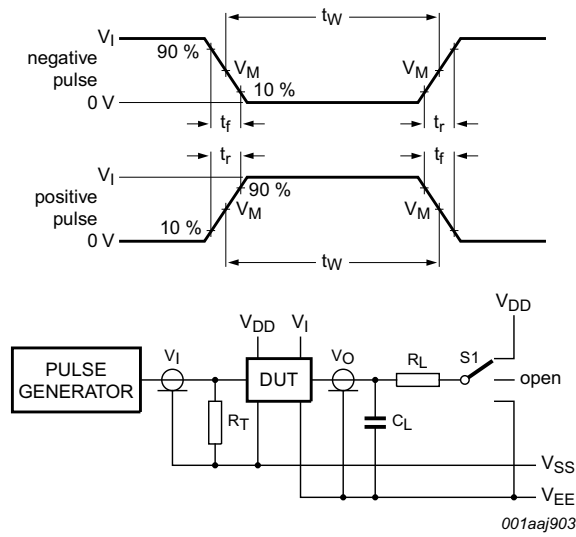


Table 9. Measurement points

Supply voltage	Input	Output
$V_{DD}$	$V_M$	$V_M$
5 V to 15 V	$0.5V_{DD}$	$0.5V_{DD}$



Test data is given in [Table 10](#).

Definitions:

DUT = Device Under Test.

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = Load capacitance including test jig and probe.

$R_L$  = Load resistance.

Fig 15. Test circuit for measuring switching times

Table 10. Test data

Input				Load		S1 position				
nYn, nZ	Sn and $\bar{E}$	$t_r, t_f$	$V_M$	$C_L$	$R_L$	$t_{PHL}$ [1]	$t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$	other
$V_{DD}$ or $V_{EE}$	$V_{DD}$ or $V_{SS}$	$\leq 20$ ns	$0.5V_{DD}$	50 pF	10 k $\Omega$	$V_{DD}$ or $V_{EE}$	$V_{EE}$	$V_{EE}$	$V_{DD}$	$V_{EE}$

[1] For nYn to nZ or nZ to nYn propagation delays use  $V_{EE}$ . For Sn to nYn or nZ propagation delays use  $V_{DD}$ .

11.2 Additional dynamic parameters

Table 11. Additional dynamic characteristics

$V_{SS} = V_{EE} = 0\text{ V}$ ;  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

Symbol	Parameter	Conditions	$V_{DD}$	Typ	Max	Unit
THD	total harmonic distortion	see Figure 16; $R_L = 10\text{ k}\Omega$ ; $C_L = 15\text{ pF}$ ; channel ON; $V_I = 0.5V_{DD}$ (p-p); $f_i = 1\text{ kHz}$	5 V [1]	0.25	-	%
			10 V [1]	0.04	-	%
			15 V [1]	0.04	-	%
$f_{(-3dB)}$	-3 dB frequency response	see Figure 17; $R_L = 1\text{ k}\Omega$ ; $C_L = 5\text{ pF}$ ; channel ON; $V_I = 0.5V_{DD}$ (p-p)	5 V [1]	13	-	MHz
			10 V [1]	40	-	MHz
			15 V [1]	70	-	MHz
$\alpha_{iso}$	isolation (OFF-state)	see Figure 18; $f_i = 1\text{ MHz}$ ; $R_L = 1\text{ k}\Omega$ ; $C_L = 5\text{ pF}$ ; channel OFF; $V_I = 0.5V_{DD}$ (p-p)	10 V [1]	-50	-	dB
$V_{ct}$	crosstalk voltage	digital inputs to switch; see Figure 19; $R_L = 10\text{ k}\Omega$ ; $C_L = 15\text{ pF}$ ; $E$ or $S_n = V_{DD}$ (square-wave)	10 V	50	-	mV
Xtalk	crosstalk	between switches; see Figure 20; $f_i = 1\text{ MHz}$ ; $R_L = 1\text{ k}\Omega$ ; $V_I = 0.5V_{DD}$ (p-p)	10 V [1]	-50	-	dB

[1]  $f_i$  is biased at  $0.5 V_{DD}$ ;  $V_I = 0.5V_{DD}$  (p-p).

Table 12. Dynamic power dissipation  $P_D$

$P_D$  can be calculated from the formulas shown;  $V_{EE} = V_{SS} = 0\text{ V}$ ;  $t_r = t_f \leq 20\text{ ns}$ ;  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

Symbol	Parameter	$V_{DD}$	Typical formula for $P_D$ ( $\mu\text{W}$ )	where:
$P_D$	dynamic power dissipation	5 V	$P_D = 2500 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	$f_i$ = input frequency in MHz; $f_o$ = output frequency in MHz; $C_L$ = output load capacitance in pF; $V_{DD}$ = supply voltage in V; $\Sigma(C_L \times f_o)$ = sum of the outputs.
		10 V	$P_D = 11500 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	
		15 V	$P_D = 29000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	

11.2.1 Test circuits

001aa904

001aa905

**Fig 16. Test circuit for measuring total harmonic distortion**

**Fig 17. Test circuit for measuring frequency response**

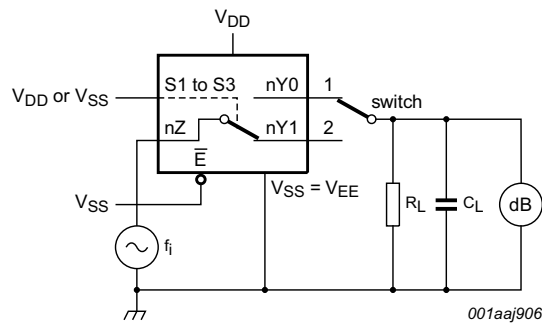
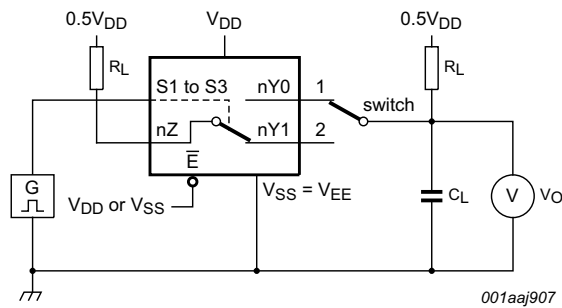
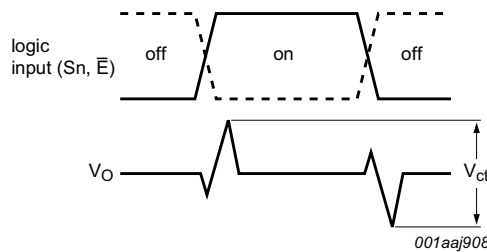


Fig 18. Test circuit for measuring isolation (OFF-state)

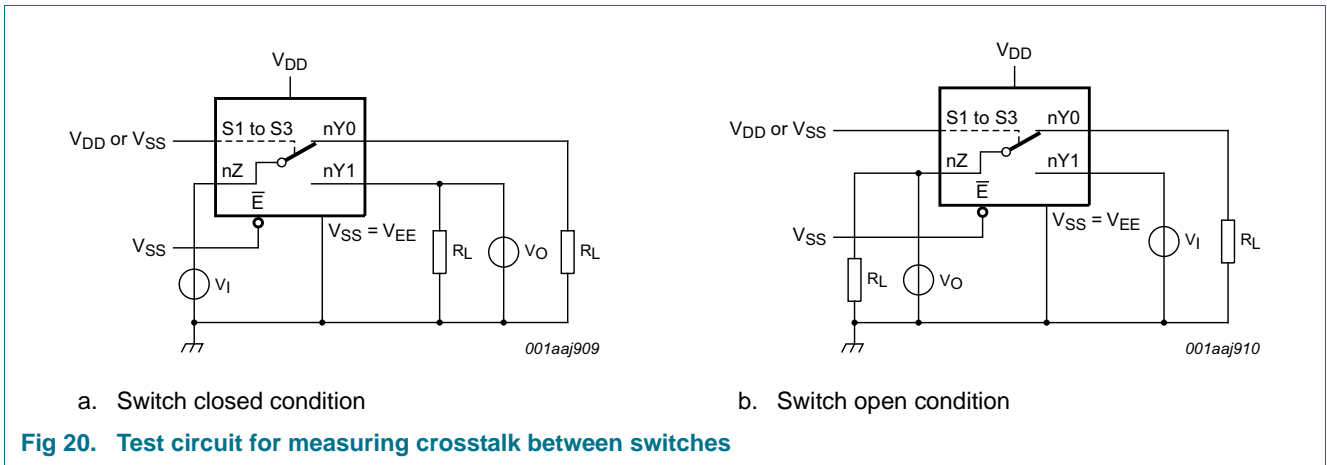


a. Test circuit



b. Input and output pulse definitions

Fig 19. Test circuit for measuring crosstalk voltage between digital inputs and switch



12. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



Fig 21. Package outline SOT109-1 (SO16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

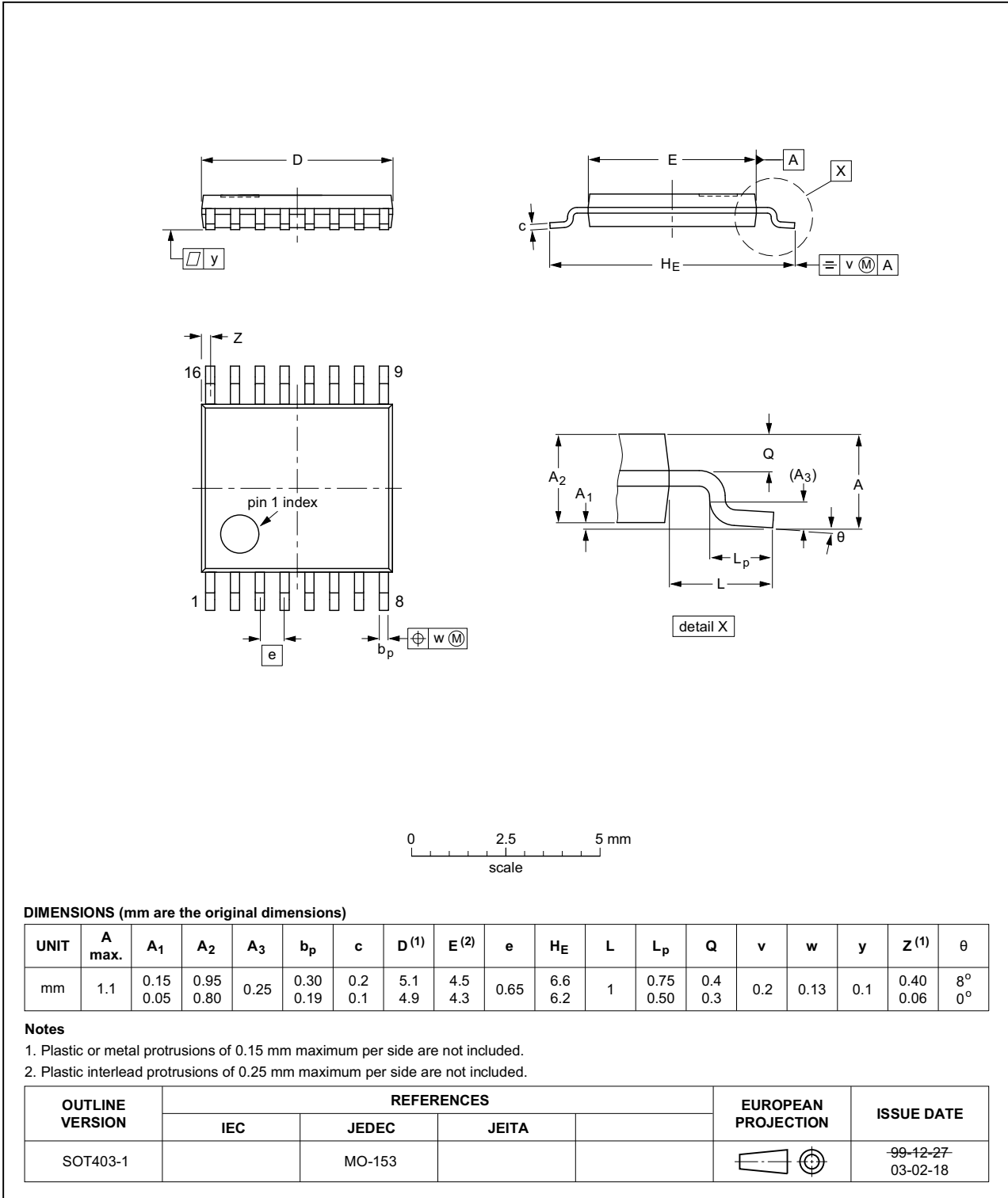


Fig 22. Package outline SOT403-1 (TSSOP16)

## 13. Abbreviations

Table 13. Abbreviations

Acronym	Description
DUT	Device Under Test

## 14. Revision history

Table 14. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4053B v.12	20160325	Product data sheet	-	HEF4053B v.11
Modifications:	<ul style="list-style-type: none"> <li>Type number HEF4053BP (SOT38-4) removed.</li> </ul>			
HEF4053B v.11	20140911	Product data sheet	-	HEF4053B v.10
Modifications:	<ul style="list-style-type: none"> <li><a href="#">Figure 19</a>: Test circuit modified</li> </ul>			
HEF4053B v.10	20111117	Product data sheet	-	HEF4053B v.9
Modifications:	<ul style="list-style-type: none"> <li>Legal pages updated.</li> <li>Changes in “General description”, “Features and benefits” and “Applications”.</li> </ul>			
HEF4053B v.9	20100325	Product data sheet	-	HEF4053B v.8
HEF4053B v.8	20100224	Product data sheet	-	HEF4053B v.7
HEF4053B v.7	20091127	Product data sheet	-	HEF4053B v.6
HEF4053B v.6	20090924	Product data sheet	-	HEF4053B v.5
HEF4053B v.5	20090825	Product data sheet	-	HEF4053B v.4
HEF4053B v.4	20090713	Product data sheet	-	HEF4053B_CNV v.3
HEF4053B_CNV v.3	19950101	Product specification	-	HEF4053B_CNV v.2
HEF4053B_CNV v.2	19950101	Product specification	-	-



## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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